| IPC ASSOCIATION CONNECTED ELECTRONICS INDUSTRI | Material Composi © Copyright 2005. IPC international and Pan-A | Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions. | | | | This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility. | | | | | | | | | |
|--|--|---|---------------------------|---------------------|------------------------------------|---|---|--------------------|-----------|-------------------------|-------------------|---------------------------------|-----|-----------|--|
| 752-21.1 | | IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute | | | | * | Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi | | | | | als and Mfg Information | | | |
| upplier Infor | | | | | | | | | , | | | | | | |
| Company name* Company unique I | | | que ID | Unique ID Authority | | | | Response Date* | | | | | | | |
| onsemi | | | | | | | | | | | 2024-05 | 2024-05-11 | | | |
| Contact Name | | Tit | Title - Contact | | | I | Phone - Contact* | | | Email - | Email - Contact* | | | | |
| Product-Env-Ste | wards | Pro | Product Enviro Compliance | | | | NA | | | | Produc | Product-Env-Stewards@onsemi.com | | | |
| uthorized Repre | esentative* | Tit | Title - Representative | | | I | Phone - Representative* | | | Email - Representative* | | | | | |
| Product-Env-Stewards Product Enviro Com | | | ro Compliance | | NA Product-Env-Stewards@onsemi.com | | | | | m | | | | | |
| Reque | ester Item Number | Mfr Item Nu | Number Mfr Item Name | | | | Effective Date | Version | n N | Manufacturing Site | | Weight* | UOM | Unit Type | |
| | | AR0132AT6 A0-TPBR | 6R00XPE | 1.2 MP 1/3 CIS | | | 2024-05-11 | | 7 | ΓWU | | 198.94 | mg | Each | |
| Ianufacturin | g Proccess Informatio | n | | | | | | | | | | | | | |
| Terminal Plating / Grid Array Material Terminal Base Alloy | | | J-STD-020 MS | L Rating | Peak Proc | ess Body | remperatui | e Max Time at Peal | k Tempera | ture Numb | per of Reflow Cyc | les | | | |
| SnAgCu CU Alloy | | Alloy | 3 | 3 | | 260 | | C | 30 | secor | nds 3 | | | | |
| omments | | | | | | | | | | | | | | | |
| TTENTION: M | SL 3 Rated item requires B | Bake and Dry F | Pack (after | electrical test) | | | | | | | | | | | |
| or more informa | ation regarding material co | mposition plea | ase refer to | page 3 | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | Declaration Type * | Detail | ed |
|--|---|---|---|---|---|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | | ium (Cr6+), Polybrominated Biphenyls (PB) | erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a | | |
| cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan | nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C | enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega | s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this | dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ | homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of |
| RoHS Declaration * 1 - Item | (s) does not contain RoHS restricted substar | nces per the definition above | Supplier A | cceptance * | Accepted |
| Exemption: If the declared item does not applicable exemptions. | contain RoHS restricted substances per t | he definition above except for defined Rol | IS exemptions, then select the corresponding | response in the R | oHS Declaration above and choose all |
| Exemption List Version | EL-2011/534/EU | | | | |
| Declaration Signature | | | | | |
| | | | | | |
| | | e "Accepted" on the Supplier Acceptance | drop-down. This will display the signature a | rea. Digitally sign t | the declaration (if required by the |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|--|------------------|--------|---------|-----------------|
| Die | 46.746 | mg | | Misc. | proprietary data | | 0.1776 | mg |
| | | | Supplier | Silicon (Si) | 7440-21-3 | | 46.1056 | mg |
| | | | Supplier | Aluminum (Al) | 7429-90-5 | | 0.4628 | mg |
| Die Attach | 2.852 | mg | | Bismaleimide Monomer | proprietary data | | 1.098 | mg |
| | | | Supplier | POLY(ETHYLENE GLYCOL) PHENYL ETHER ACRYLATE | 56641-05-5 | | 0.0143 | mg |
| | | | Supplier | 2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate | 55818-57-0 | | 0.2852 | mg |
| | | | Supplier | Bis(4-tert-butylcyclohexyl) peroxydicarbonate | 15520-11-3 | | 0.0143 | mg |
| | | | Supplier | 2,2-dimethyl-1,3-propanediyl dimethacrylate | 1985-51-9 | | 0.2852 | mg |
| | | | Supplier | 2-phenoxy ethyl acrylate | 48145-04-6 | | 0.2852 | mg |
| | | | Supplier | Bisphenol A_Epichlorohydrin Polymer | 25068-38-6 | | 0.0143 | mg |
| | | | Supplier | Other Additive Agents | Proprietary Data | | 0.5704 | mg |
| | | | Supplier | Formaldehyde Polymer | 9003-36-5 | | 0.2852 | mg |
| Imaging Lens | 29.239 | mg | Supplier | Titanium Dioxide (TiO2) | 13463-67-7 | | 1.5388 | mg |
| | | | Supplier | Sodium Monoxide (Na2O) | 1313-59-3 | | 1.5388 | mg |
| | | | Supplier | Zinc Monoxide (ZnO) | 1314-13-2 | | 1.5388 | mg |
| | | | В | Antimony Trioxide (Sb2O3) | 1309-64-4 | | 0.1541 | mg |
| | | | Supplier | Aluminum Trioxide (Al2O3) | 1344-28-1 | | 1.5388 | mg |
| | | | Supplier | Potassium Monoxide (K2O) | 12136-45-7 | | 1.5388 | mg |
| | | | Supplier | Silica Crystalline (SiO2) | 14808-60-7 | | 21.3907 | mg |
| Lid Attach | 1.459 | mg | Supplier | 2,2-Bis(glycidyloxyphenyl)propane polymer | 25085-99-8 | | 0.3647 | mg |
| | | | Supplier | 3,4-EPOXYCYCLOHEXYLMETHYL | 2386-87-0 | | 1.0578 | mg |
| | | | Supplier | Misc. | Proprietary Data | | 0.0365 | mg |
| Mold Compound | 43.49 | mg | | Epoxy resin | proprietary data | | 10.7855 | mg |
| | | | Supplier | Other Additive Agents | Proprietary Data | | 1.3917 | mg |
| | | | Supplier | Silica Amorphous (SiO2) | 7631-86-9 | | 4.349 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 25.6591 | mg |
| | | | Supplier | Silica Crystalline (SiO2) | 14808-60-7 | | 1.3047 | mg |
| Solder Ball | 35.868 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 1.076 | mg |

| | | | Supplier | Tin (Sn) | 7440-31-5 | 34.6126 | mg |
|---------------------------|-------|----|----------|------------------------|------------------|---------|----|
| | | | Supplier | Copper (Cu) | 7440-50-8 | 0.1793 | mg |
| Solder Mask | 4.22 | mg | | Epoxy resin | proprietary data | 0.5064 | mg |
| | | | Supplier | Acrylate | Proprietary Data | 1.612 | mg |
| | | | Supplier | Talc | 14807-96-6 | 0.1139 | mg |
| | | | Supplier | Miscellaneous | Trade Secret | 0.1561 | mg |
| | | | Supplier | Barium Sulfate (BaSO4) | 7727-43-7 | 1.8315 | mg |
| Substrate Copper Foil | 3.09 | mg | Supplier | Copper (Cu) | 7440-50-8 | 3.09 | mg |
| Substrate - Core Material | 16.24 | mg | | Epoxy resin | proprietary data | 3.5192 | mg |
| | | | Supplier | Fiber Glass (SiO2) | 65997-17-3 | 12.7208 | mg |
| Substrate Plating-Au | 0.29 | mg | Supplier | Gold (Au) | 7440-57-5 | 0.29 | mg |
| Substrate Plating-Cu | 14.49 | mg | Supplier | Copper (Cu) | 7440-50-8 | 14.49 | mg |
| Substrate Plating-Ni | 0.67 | mg | В | Nickel (Ni) | 7440-02-0 | 0.67 | mg |
| Wire Bond - Au | 0.286 | mg | Supplier | Gold (Au) | 7440-57-5 | 0.286 | mg |